

RELEASE FILM ECO 25

ROUGH SURFACE

ECO25 RS– Release Film is a very economical solution to be used in all different types of lamination processes. The maximum laminating temperature is 200°C. ECO25 RS– Release Film is an inert or non reactive material and leaves no residues on the PCB –surfaces. Excellent functional and dimensional properties under common

thermal conditions and high pressure guarantees a very easy release.
Typical usage: FPC, Rigid-Flex PCB, HDI and CCL lamination

PROPERTIES

Thermal usage in the hot press	max. 200 °C (392 °F) for 90min.	
Melting point	250 °C ± 10 °C	
Density	1.400 gcm ⁻³	ASTM-D1505
Tensile strength	MD ≥ 210 Nmm ⁻² TD ≥ 210 Nmm ⁻²	ASTM D882A ASTM D882A
Elongation at break (v= 50mmmin ⁻¹)	MD ≥ 125 % TD ≥ 110 %	ASTM D882A ASTM D882A
Heat shrinkage (150°C / 30min.)	MD ≤ 3.5 % TD ≤ 1,2 %	ASTM D1204 ASTM D1204
Coefficient of friction (static) Coefficient of friction (dynamic)	0.37 0.28	ASTM D1894 ASTM D1894
Decomposition temperature	> 270 °C	
Moisture absorption	< 0.9 % at common room conditions	
Appearance	White	
Haze	78 %	ASTM-D1003
Surface	Matt - both sides, Ra < 5,4 µm	
Storage Life	> 1 year at room temperature	
Thickness	25, 38, 50 µm – 1.0, 1.5, 2.0 m,	
Length of film	1067 / 1000 / 500 m	
Roll widths	660, 680, 991, 1295 mm	

Subject to changes due to technical improvements without prior notice.

Other dimensions on request.